

Title (en)
POLYAMIDE MOLDING COMPOUNDS

Title (de)
POLYAMID-FORMMASSEN

Title (fr)
MATIÈRES À MOULER EN POLYAMIDE

Publication
EP 2758471 A1 20140730 (DE)

Application
EP 12761580 A 20120912

Priority
• EP 11182184 A 20110921
• EP 2012067796 W 20120912
• EP 12761580 A 20120912

Abstract (en)
[origin: EP2573138A1] Thermoplastic molding compound comprises (a) 80-99.5 wt.% a polyamide; (b) 0.5-20 wt.% of a co-polyester; (c) 0-60 wt.% of fibrous reinforcement material; and (d) 0-10 wt.% of further additives, where the co-polyester comprises (b1) 40-80 wt.% of succinic acid, adipic acid, azelaic acid, sebacic acid, brassylic acid and/or its ester-forming derivatives, (b2) 20-60 wt.% of terephthalic acid and/or its ester forming derivatives, (b3) 98-102 mol.% of 1,4 butanediol and/or 1,3-propanediol, (b4) 0-1 wt.% of a splitter, (b5) 0-2 wt.% of a chain extender and (b6) 0-2 wt.% of further additives. Thermoplastic molding compound comprises (a) 80-99.5 wt.% a polyamide; (b) 0.5-20 wt.% of a co-polyester having a viscosity number, according to DIN 53728, of 150-320 cm³/g; (c) 0-60 wt.% of fibrous reinforcement material; and (d) 0-10 wt.% of further additives, where the co-polyester comprises (b1) 40-80 wt.% of succinic acid, adipic acid, azelaic acid, sebacic acid, brassylic acid and/or its ester-forming derivatives, (b2) 20-60 wt.% of terephthalic acid and/or its ester forming derivatives, (b3) 98-102 mol.% of 1,4 butanediol and/or 1,3-propanediol, as a diol component, (b4) 0-1 wt.% of a splitter, (b5) 0-2 wt.% of a chain extender and (b6) 0-2 wt.% of further additives.

IPC 8 full level
C08L 77/00 (2006.01); **C08L 67/02** (2006.01); **C08L 77/02** (2006.01)

CPC (source: CN EP US)
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C-Set (source: CN EP US)

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EP US
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